FEATUES

• Operates From Single 5V Supply
• Input Current: 150 nA Max. Over Temperature
• Offset Current: 20 nA Max. Over Temperature
• Differential Input Voltage Range: ±30V
• Power Consumption: 135 mW at ±15V

DESCRIPTION

The LM111-N, LM211-N and LM311-N are voltage comparators that have input currents nearly a thousand times lower than devices like the LM106 or LM710. They are also designed to operate over a wider range of supply voltages: from standard ±15V op amp supplies down to the single 5V supply used for IC logic. Their output is compatible with RTL, DTL and TTL as well as MOS circuits. Further, they can drive lamps or relays, switching voltages up to 50V at currents as high as 50 mA.

Typical Applications

NOTE

Pin connections shown in Schematic Diagram and Typical Applications are for the LMC TO-99 package.

Figure 1. Offset Balancing

Do Not Ground Strobe Pin. Output is turned off when current is pulled from Strobe Pin.

Figure 2. Strobing

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Increases typical common mode slew from 7.0V/μs to 18V/μs.

**Figure 3. Increasing Input Stage Current**

**Figure 4. Detector for Magnetic Transducer**

*Absorbs inductive kickback of relay and protects IC from severe voltage transients on V++ line.

*Do Not* Ground Strobe Pin.

**Figure 5. Digital Transmission Isolator**

**Figure 6. Relay Driver with Strobe**

*Solid tantalum

*Do Not* Ground Strobe Pin.

Typical input current is 50 pA with inputs strobed off.

Pin connections shown in Schematic Diagram and Typical Applications are for the LMC TO-99 package.

**Figure 7. Strobing off Both Input and Output Stages**

**Figure 8. Positive Peak Detector**
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Figure 9. Zero Crossing Detector Driving MOS Logic
Absolute Maximum Ratings for the LM111-N/LM211-N(1)(2)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Total Supply Voltage (V_{84})</td>
<td></td>
<td>36V</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output to Negative Supply Voltage (V_{74})</td>
<td></td>
<td>50V</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Ground to Negative Supply Voltage (V_{14})</td>
<td></td>
<td>30V</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Differential Input Voltage</td>
<td></td>
<td>±30V</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Voltage(3)</td>
<td></td>
<td>±15V</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output Short Circuit Duration</td>
<td></td>
<td>10 sec</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating Temperature Range</td>
<td>LM111-N</td>
<td>−55°C to 125°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>LM211-N</td>
<td>−25°C to 85°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Lead Temperature (Soldering, 10 sec)</td>
<td></td>
<td>260°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Voltage at Strobe Pin</td>
<td>V^+−5V</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Soldering Information</td>
<td>Dual-In-Line Package</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Soldering (10 seconds)</td>
<td>260°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Small Outline Package</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Vapor Phase (60 seconds)</td>
<td>215°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Infrared (15 seconds)</td>
<td>220°C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>ESD Rating(4)</td>
<td></td>
<td>300V</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) Refer to RETS111X for the LM111H, LM111J and LM111J-8 military specifications.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
(3) This rating applies for ±15 supplies. The positive input voltage limit is 30V above the negative supply. The negative input voltage limit is equal to the negative supply voltage or 30V below the positive supply, whichever is less.
(4) Human body model, 1.5 kΩ in series with 100 pF.

Electrical Characteristics(1) for the LM111-N and LM211-N

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Offset Voltage(2)</td>
<td>T_{A}=25°C, R_{S}≤50k</td>
<td>0.7</td>
<td>3.0</td>
<td></td>
<td>mV</td>
</tr>
<tr>
<td>Input Offset Current</td>
<td>T_{A}=25°C</td>
<td>4.0</td>
<td>10</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Input Bias Current</td>
<td>T_{A}=25°C</td>
<td>60</td>
<td>100</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Voltage Gain</td>
<td>T_{A}=25°C</td>
<td>40</td>
<td>200</td>
<td>V/mV</td>
<td></td>
</tr>
<tr>
<td>Response Time(3)</td>
<td>T_{A}=25°C</td>
<td>200</td>
<td></td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>Saturation Voltage</td>
<td>V_{IN}≤5 mV, I_{OUT}=50 mA</td>
<td>0.75</td>
<td>1.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td>T_{A}=25°C</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Strobe ON Current(4)</td>
<td>T_{A}=25°C</td>
<td>2.0</td>
<td>5.0</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Output Leakage Current</td>
<td>V_{IN}≥5 mV, V_{OUT}=35V, T_{A}=25°C, I_{STROBE}=3 mA</td>
<td>0.2</td>
<td>10</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Input Offset Voltage(2)</td>
<td>R_{S}≤50 k</td>
<td>4.0</td>
<td></td>
<td>mV</td>
<td></td>
</tr>
<tr>
<td>Input Offset Current(2)</td>
<td></td>
<td>20</td>
<td>nA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Bias Current</td>
<td></td>
<td>150</td>
<td>nA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Voltage Range</td>
<td>V^+=15V, V^−=−15V, Pin 7 Pull-Up</td>
<td>−14.5</td>
<td>13.8-14.7</td>
<td>13.0</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>May Go To 5V</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Saturation Voltage</td>
<td>V^+≥4.5V, V^−=0, V_{IN}≤−6 mV, I_{OUT}=8 mA</td>
<td>0.23</td>
<td>0.4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Output Leakage Current</td>
<td></td>
<td>0.1</td>
<td>0.5</td>
<td>μA</td>
<td></td>
</tr>
<tr>
<td>Positive Supply Current</td>
<td>T_{A}=25°C</td>
<td>5.1</td>
<td>6.0</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Negative Supply Current</td>
<td>T_{A}=25°C</td>
<td>4.1</td>
<td>5.0</td>
<td>mA</td>
<td></td>
</tr>
</tbody>
</table>

(1) These specifications apply for V_{ES}=±15V and Ground pin at ground, and −55°C≤T_{A}≤+125°C, unless otherwise stated. With the LM211-N, however, all temperature specifications are limited to −25°C≤T_{A}≤+85°C. The offset voltage, offset current and bias current specifications apply for any supply voltage from a single 5V supply up to ±15V supplies.
(2) The offset voltages and offset currents given are the maximum values required to drive the output within a volt of either supply with a 1 mA load. Thus, these parameters define an error band and take into account the worst-case effects of voltage gain and R_{S}.
(3) The response time specified (see definitions) is for a 100 mV input step with 5 mV overdrive.
(4) This specification gives the range of current which must be drawn from the strobe pin to ensure the output is properly disabled. Do not short the strobe pin to ground; it should be current driven at 3 to 5 mA.
Absolute Maximum Ratings for the LM311-N

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Total Supply Voltage (V_{SD})</td>
<td></td>
<td></td>
<td></td>
<td>36V</td>
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<tr>
<td>Output to Negative Supply Voltage (V_{HD})</td>
<td></td>
<td></td>
<td></td>
<td>40V</td>
<td></td>
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<tr>
<td>Ground to Negative Supply Voltage (V_{LD})</td>
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<td></td>
<td></td>
<td>30V</td>
<td></td>
</tr>
<tr>
<td>Differential Input Voltage</td>
<td></td>
<td></td>
<td></td>
<td>±30V</td>
<td></td>
</tr>
<tr>
<td>Input Voltage</td>
<td></td>
<td></td>
<td></td>
<td>±15V</td>
<td></td>
</tr>
<tr>
<td>Power Dissipation</td>
<td></td>
<td></td>
<td></td>
<td>500 mW</td>
<td></td>
</tr>
<tr>
<td>ESD Rating</td>
<td></td>
<td></td>
<td></td>
<td>300V</td>
<td></td>
</tr>
<tr>
<td>Output Short Circuit Duration</td>
<td></td>
<td></td>
<td></td>
<td>10 sec</td>
<td></td>
</tr>
<tr>
<td>Operating Temperature Range</td>
<td></td>
<td></td>
<td></td>
<td>0° to 70°C</td>
<td></td>
</tr>
<tr>
<td>Storage Temperature Range</td>
<td></td>
<td></td>
<td></td>
<td>−65°C to 150°C</td>
<td></td>
</tr>
<tr>
<td>Lead Temperature (soldering, 10 sec)</td>
<td></td>
<td></td>
<td></td>
<td>260°C</td>
<td></td>
</tr>
<tr>
<td>Voltage at Strobe Pin</td>
<td></td>
<td>V^*−5V</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Soldering Information

<table>
<thead>
<tr>
<th>Package</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dual-In-Line</td>
<td>Soldering (10 seconds)</td>
<td>60°C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Small Outline</td>
<td>Vapor Phase (60 seconds)</td>
<td></td>
<td></td>
<td>215°C</td>
</tr>
<tr>
<td></td>
<td>Infrared (15 seconds)</td>
<td></td>
<td></td>
<td>220°C</td>
</tr>
</tbody>
</table>

(1) “Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.”

(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

(3) This rating applies for ±15V supplies. The positive input voltage limit is 30V above the negative supply. The negative input voltage limit is equal to the negative supply voltage or 30V below the positive supply, whichever is less.

(4) The maximum junction temperature of the LM311-N is 110°C. For operating at elevated temperature, devices in the LMC package must be derated based on a thermal resistance of 165°C/W, junction to ambient, or 20°C/W, junction to case. The thermal resistance of the dual-in-line package is 100°C/W, junction to ambient.

(5) Human body model, 1.5 kΩ in series with 100 pF.

Electrical Characteristics

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Offset Voltage</td>
<td></td>
<td>2.0</td>
<td>7.5</td>
<td>mV</td>
<td></td>
</tr>
<tr>
<td>Input Offset Current</td>
<td></td>
<td>6.0</td>
<td>50</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Input Bias Current</td>
<td></td>
<td>100</td>
<td>250</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Voltage Gain</td>
<td></td>
<td>40</td>
<td>200</td>
<td>V/mV</td>
<td></td>
</tr>
<tr>
<td>Response Time</td>
<td></td>
<td>200</td>
<td>ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Saturation Voltage</td>
<td></td>
<td>0.75</td>
<td>1.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Strobe ON Current</td>
<td></td>
<td>2.0</td>
<td>5.0</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Output Leakage Current</td>
<td></td>
<td>0.2</td>
<td>50</td>
<td>nA</td>
<td></td>
</tr>
<tr>
<td>Input Offset Voltage</td>
<td>R_{S}=50K</td>
<td>10</td>
<td>mV</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Offset Current</td>
<td></td>
<td>70</td>
<td>nA</td>
<td></td>
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<tr>
<td>Input Bias Current</td>
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<td>300</td>
<td>nA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Voltage Range</td>
<td></td>
<td>−14.5</td>
<td>13.8,−14.7</td>
<td>13.0</td>
<td>V</td>
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<tr>
<td>Saturation Voltage</td>
<td></td>
<td>0.23</td>
<td>0.4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Positive Supply Current</td>
<td></td>
<td>5.1</td>
<td>7.5</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Negative Supply Current</td>
<td></td>
<td>4.1</td>
<td>5.0</td>
<td>mA</td>
<td></td>
</tr>
</tbody>
</table>

(1) These specifications apply for V_{S}=±15V and Pin 1 at ground, and 0°C < T_{A} < +70°C, unless otherwise specified. The offset voltage, offset current and bias current specifications apply for any supply voltage from a single 5V supply up to ±15V supplies.

(2) The offset voltages and offset currents given are the maximum values required to drive the output within a volt of either supply with 1 mA load. Thus, these parameters define an error band and take into account the worst-case effects of voltage gain and R_{S}.

(3) The response time specified (see definitions) is for a 100 mV input step with 5 mV overdrive.

(4) This specification gives the range of current which must be drawn from the strobe pin to ensure the output is properly disabled. Do not short the strobe pin to ground; it should be current driven at 3 to 5 mA.
Typical Performance Characteristics LM111-N/LM211-N

**Input Bias Current**

- $V_O = \pm 15V$
- RAISED
- SHORT PINS
- 5, 6, AND 8

**Input Offset Current**

- $V_O = \pm 15V$
- RAISED
- SHORT PINS
- 5, 6, AND 8

**Input Bias Current**

- $V_O = \pm 15V$
- $T_A = 25^\circ C$

**Input Bias Current**

- $V_O = \pm 15V$
- $T_A = 25^\circ C$

**Input Bias Current**

- Referred to Supply Voltages

**Common Mode Limits**

- $V^+$
- $-0.5$ to $-1.0$
- $-1.5$
- $-55$ to $125^\circ C$

**Common Mode Limits**

- $V^-$
- $0.2$ to $0.4$
- $-55$ to $125^\circ C$

**Output Voltage**

- Emitter Follower Output
- $R_o = 600Q$
- $V_O = 30V$
- $T_A = 25^\circ C$

**Output Voltage**

- $V^+$
- $50V$
- $-5$ to $0$

**Temperature (°C)**

- Figure 10.
- Figure 11.
- Figure 12.
- Figure 13.
- Figure 14.
- Figure 15.
Typical Performance Characteristics LM111-N/LM211-N (continued)

**Input Bias Current**

Figure 16.

**Input Overdrives**

Figure 17.

**Response Time for Various Input Bias Current**

Figure 18.

**Response Time for Various Input Overdrives**

Figure 19.

**Output Limiting Characteristics**

Figure 20.

Figure 21.
Typical Performance Characteristics LM111-N/LM211-N (continued)

- **Supply Current**
  - Figure 22.

- **Leakage Currents**
  - Figure 24.
Typical Performance Characteristics LM311-N

Input Bias Current

![Input Bias Current Graph](image)

**Figure 25.**

Input Offset Current

![Input Offset Current Graph](image)

**Figure 26.**

Offset Error

![Offset Error Graph](image)

**Figure 27.**

Input Characteristics

![Input Characteristics Graph](image)

**Figure 28.**

Common Mode Limits

![Common Mode Limits Graph](image)

**Figure 29.**

Transfer Function

![Transfer Function Graph](image)

**Figure 30.**
Typical Performance Characteristics LM311-N (continued)

Response Time for Various Input Overdrives

![Response Time for Various Input Overdrives](image)

Output Saturation Voltage

![Output Saturation Voltage](image)

Response Time for Various Input Overdrives

![Response Time for Various Input Overdrives](image)

Response Time for Various Input Overdrives

![Response Time for Various Input Overdrives](image)

Output Limiting Characteristics

![Output Limiting Characteristics](image)
Typical Performance Characteristics LM311-N (continued)

Supply Current

$T_A = 25^\circ C$

- POSITIVE SUPPLY - OUTPUT LOW
- POSITIVE AND NEGATIVE SUPPLY - OUTPUT HIGH

**Figure 37.**

Supply Current

$V_S = \pm 15V$

- POSITIVE SUPPLY - OUTPUT LOW
- POSITIVE AND NEGATIVE SUPPLY - OUTPUT HIGH

**Figure 38.**

Leakage Currents

$V_S = \pm 15V$

- OUTPUT $V_{OUT} = 40V$
- INPUT $V_{IN} = 15V$

**Figure 39.**
APPLICATION HINTS

CIRCUIT TECHNIQUES FOR AVOIDING OSCILLATIONS IN COMPARATOR APPLICATIONS

When a high-speed comparator such as the LM111-N is used with fast input signals and low source impedances, the output response will normally be fast and stable, assuming that the power supplies have been bypassed (with 0.1 µF disc capacitors), and that the output signal is routed well away from the inputs (pins 2 and 3) and also away from pins 5 and 6.

However, when the input signal is a voltage ramp or a slow sine wave, or if the signal source impedance is high (1 kΩ to 100 kΩ), the comparator may burst into oscillation near the crossing-point. This is due to the high gain and wide bandwidth of comparators like the LM111-N. To avoid oscillation or instability in such a usage, several precautions are recommended, as shown in Figure 40 below.

1. The trim pins (pins 5 and 6) act as unwanted auxiliary inputs. If these pins are not connected to a trim-pot, they should be shorted together. If they are connected to a trim-pot, a 0.01 µF capacitor C1 between pins 5 and 6 will minimize the susceptibility to AC coupling. A smaller capacitor is used if pin 5 is used for positive feedback as in Figure 40.

2. Certain sources will produce a cleaner comparator output waveform if a 100 pF to 1000 pF capacitor C2 is connected directly across the input pins.

3. When the signal source is applied through a resistive network, R<sub>S</sub>, it is usually advantageous to choose an R<sub>S</sub> of substantially the same value, both for DC and for dynamic (AC) considerations. Carbon, tin-oxide, and metal-film resistors have all been used successfully in comparator input circuitry. Inductive wirewound resistors are not suitable.

4. When comparator circuits use input resistors (eg. summing resistors), their value and placement are particularly important. In all cases the body of the resistor should be close to the device or socket. In other words there should be very little lead length or printed-circuit foil run between comparator and resistor to radiate or pick up signals. The same applies to capacitors, pots, etc. For example, if R<sub>S</sub>=10 kΩ, as little as 5 inches of lead between the resistors and the input pins can result in oscillations that are very hard to damp. Twisting these input leads tightly is the only (second best) alternative to placing resistors close to the comparator.

5. Since feedback to almost any pin of a comparator can result in oscillation, the printed-circuit layout should be engineered thoughtfully. Preferably there should be a groundplane under the LM111-N circuitry, for example, one side of a double-layer circuit card. Ground foil (or, positive supply or negative supply foil) should extend between the output and the inputs, to act as a guard. The foil connections for the inputs should be as small and compact as possible, and should be essentially surrounded by ground foil on all sides, to guard against capacitive coupling from any high-level signals (such as the output). If pins 5 and 6 are not used, they should be shorted together. If they are connected to a trim-pot, the trim-pot should be located, at most, a few inches away from the LM111-N, and the 0.01 µF capacitor should be installed. If this capacitor cannot be used, a shielding printed-circuit foil may be advisable between pins 6 and 7. The power supply bypass capacitors should be located within a couple inches of the LM111-N. (Some other comparators require the power-supply bypass to be located immediately adjacent to the comparator.)

6. It is a standard procedure to use hysteresis (positive feedback) around a comparator, to prevent oscillation, and to avoid excessive noise on the output because the comparator is a good amplifier for its own noise. In the circuit of Figure 41, the feedback from the output to the positive input will cause about 3 mV of hysteresis. However, if R<sub>S</sub> is larger than 100 kΩ, such as 50 kΩ, it would not be reasonable to simply increase the value of the positive feedback resistor above 510 kΩ. The circuit of Figure 42 could be used, but it is rather awkward. See the notes in paragraph 7 below.

7. When both inputs of the LM111-N are connected to active signals, or if a high-impedance signal is driving the positive input of the LM111-N so that positive feedback would be disruptive, the circuit of Figure 40 is ideal. The positive feedback is to pin 5 (one of the offset adjustment pins). It is sufficient to cause 1 to 2 mV hysteresis and sharp transitions with input triangle waves from a few Hz to hundreds of kHz. The positive-feedback signal across the 82Ω resistor swings 240 mV below the positive supply. This signal is centered around the nominal voltage at pin 5, so this feedback does not add to the V<sub>OS</sub> of the comparator. As much as 8 mV of V<sub>OS</sub> can be trimmed out, using the 5 kΩ pot and 3 kΩ resistor as shown.

8. These application notes apply specifically to the LM111-N, LM211-N, LM311-N, and LF111 families of comparators, and are applicable to all high-speed comparators in general, (with the exception that not all comparators have trim pins).
Pin connections shown are for LM111H in the LMC hermetic package.

**Figure 40. Improved Positive Feedback**

Pin connections shown are for LM111H in the LMC hermetic package.

**Figure 41. Conventional Positive Feedback**

**Figure 42. Positive Feedback with High Source Resistance**
Typical Applications

(Pin numbers refer to LMC package)

![Figure 43. Zero Crossing Detector Driving MOS Switch](image)

*TTL or DTL fanout of two

![Figure 44. 100 kHz Free Running Multivibrator](image)

*Adjust for symmetrical square wave time when $V_{IN} = 5$ mV
†Minimum capacitance 20 pF Maximum frequency 50 kHz

![Figure 45. 10 Hz to 10 kHz Voltage Controlled Oscillator](image)
*Input polarity is reversed when using pin 1 as output.

Figure 46. Driving Ground-Referred Load

*Values shown are for a 0 to 30V logic swing and a 15V threshold.
†May be added to control speed and reduce susceptibility to noise spikes.

Figure 48. TTL Interface with High Level Logic

Figure 49. Crystal Oscillator

Figure 50. Comparator and Solenoid Driver
*Solid tantalum
†Adjust to set clamp level

Figure 51. Precision Squarer

*Solid tantalum

Figure 52. Low-Voltage Adjustable Reference Supply

*Solid tantalum

Figure 53. Positive Peak Detector
Figure 54. Zero Crossing Detector Driving MOS Logic

*Solid tantalum

Figure 55. Negative Peak Detector

*R2 sets the comparison level. At comparison, the photodiode has less than 5 mV across it, decreasing leakages by an order of magnitude.

Figure 56. Precision Photodiode Comparator
Figure 57. Switching Power Amplifier

Figure 58. Switching Power Amplifier
NOTE

Pin connections shown in the schematic diagram are for the LMC package.
### Pin Diagrams

#### Top View

**Figure 59. 8-Pin TO-99**
See LMC Package

**Figure 60. 8-Pin CDIP (See NAB Package)**
8-Pin SOIC (See D Package)
8-Pin PDIP (See P Package)

**Figure 61. 14-Pin CDIP (See J Package)**
14-Pin PDIP (See NFF Package)

**Figure 62. LM111W/883, LM111WG/883**
10-Pin CLGA (See NAD Package)
10-Pin CLGA (See NAC Package)
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<th>Changes from Revision D (March 2013) to Revision E</th>
<th>Page</th>
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<td>• Changed layout of National Data Sheet to TI format</td>
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### Packaging Information

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<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
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(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- **OBSOLETE**: TI has discontinued the production of the device.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### TAPE DIMENSIONS

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<td>P1</td>
<td>Pitch between successive cavity centers</td>
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#### REEL DIMENSIONS

- **Reel Diameter**
- **Reel Width (W1)**

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

- **User Direction of Feed**
- **Sprocket Holes**

*All dimensions are nominal*

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*All dimensions are nominal*
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads in true position within 0.010 (0.25) R Ø MMC at seating plane.
D. Pin numbers shown for reference only. Numbers may not be marked on package.
E. Fails within JEDEC MO-002/10-99.
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001 variation BA.
D (R-PDSO-G8) PLASTIC SMALL OUTLINE

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0.15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0.43) each side.
E. Reference JEDEC MS-012 variation AA.

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